

**AEC-Q101 Qualified** 

# **4V Drive Pch MOSFET**

# RSD160P05FRA

### Structure

Silicon P-channel MOSFET

### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.

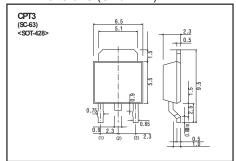
### Application

Switching

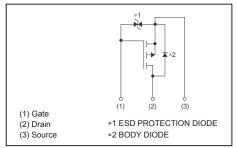
Packaging specifications

	Package	Taping
Type	Code	TL
	Basic ordering unit (pieces)	2500
RSD160P05	0	

### Dimensions (Unit : mm)



### • Inner circuit



# ●Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parai	Symbol	Limits	Unit	
Drain-source voltage		$V_{DSS}$	-45	V
Gate-source voltage		$V_{GSS}$	±20	V
Drain current	Continuous	I <sub>D</sub>	±16	Α
	Pulsed	I <sub>DP</sub> *1	±32	Α
Source current	Continuous	Is	-16	Α
(Body Diode)	Pulsed	I <sub>SP</sub> *1	-32	Α
Power dissipation	P <sub>D</sub> *2	20	W	
Channel temperature	T <sub>ch</sub>	150	°C	
Range of storage ter	T <sub>stg</sub>	-55 to +150	°C	

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1%

### Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to Case	R <sub>th (ch-c)</sub> *	6.25	°C / W

<sup>\*</sup> T<sub>c</sub>=25°C

<sup>\*2</sup> T<sub>c</sub>=25°C

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	ı	-	±10	μA	$V_{GS}=\pm20V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	-45	-	-	٧	I <sub>D</sub> =-1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	ı	-	-1	μA	$V_{DS}$ =-45V, $V_{GS}$ =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-1.0	-	-3.0	٧	$V_{DS}$ =-10V, $I_{D}$ =-1mA
Static ducin course on state	*	1	35	50		I <sub>D</sub> =-16A, V <sub>GS</sub> =-10V
Static drain-source on-state resistance	R <sub>DS (on)</sub>	ı	45	63	mΩ	I <sub>D</sub> =-8A, V <sub>GS</sub> =-4.5V
		ı	50	70		I <sub>D</sub> =-8A, V <sub>GS</sub> =-4.0V
Forward transfer admittance	IY <sub>fs</sub> ľ	8.0	-	-	S	I <sub>D</sub> =-8A, V <sub>DS</sub> =-10V
Input capacitance	C <sub>iss</sub>	-	2000	-	pF	V <sub>DS</sub> =-10V
Output capacitance	C <sub>oss</sub>	-	250	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	140	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	-	13	-	ns	I <sub>D</sub> =-8.0A, V <sub>DD</sub> ≒-25V
Rise time	t <sub>r</sub> *	-	22	-	ns	V <sub>GS</sub> =-10V
Turn-off delay time	t <sub>d(off)</sub> *	-	90	-	ns	$R_L=3.1\Omega$
Fall time	t <sub>f</sub> *	-	50	-	ns	$R_G=10\Omega$
Total gate charge	Q <sub>g</sub> *	-	16.0	-	nC	V <sub>DD</sub> ≒ -25V
Gate-source charge	Q <sub>gs</sub> *	-	5.2	_	nC	I <sub>D</sub> =-16A,
Gate-drain charge	Q <sub>gd</sub> *	-	5.0	_	nC	V <sub>GS</sub> =-5V

<sup>\*</sup>Pulsed

# ●Body diode characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	-	-1.2	V	I <sub>s</sub> =-16A, V <sub>GS</sub> =0V

<sup>\*</sup>Pulsed

### ●Electrical characteristic curves (Ta=25°C)

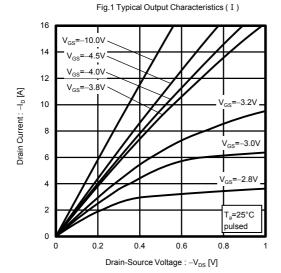


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

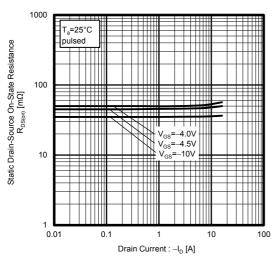


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

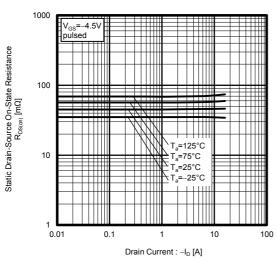


Fig.2 Typical Output Characteristics ( II )

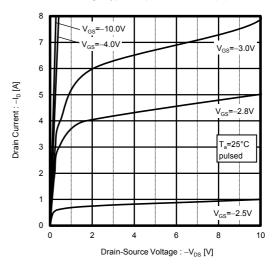


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

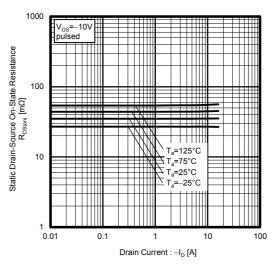


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current

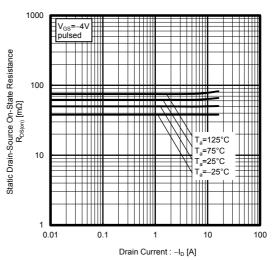


Fig.7 Forward Transfer Admittance vs. Drain Current

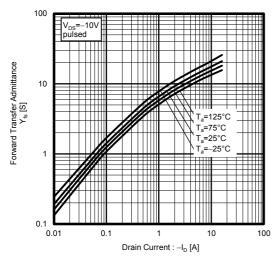
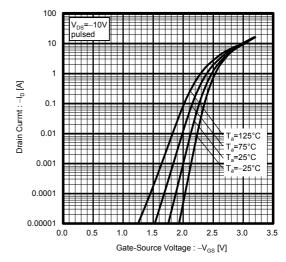


Fig.8 Typical Transfer Characteristics



Flg.9 Source Current vs. Source-Drain Voltage

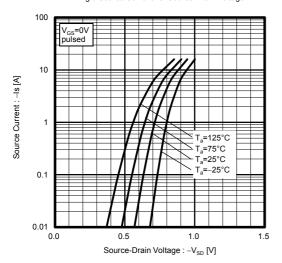


Fig.10 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

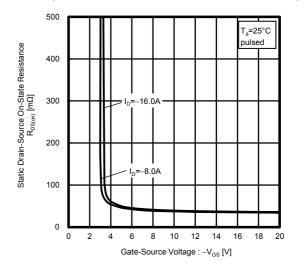


Fig.11 Switching Characteristics

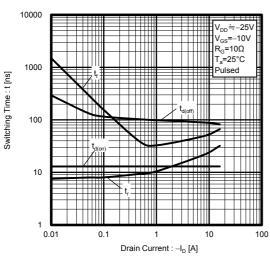
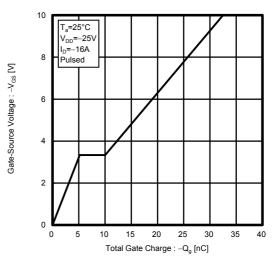
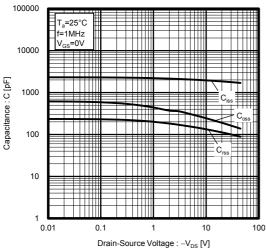


Fig.12 Dynamic Input Characteristics



T<sub>a</sub>=25°C

Flg.13 Typical Capacitance vs. Drain-Source Voltage



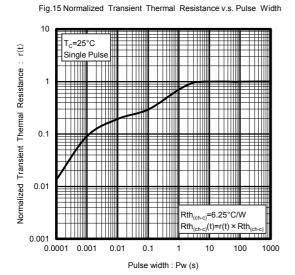
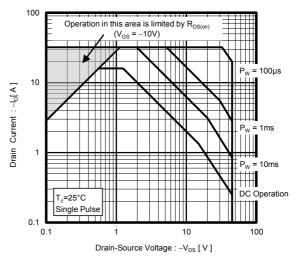


Fig.14 Maximum Safe Operating Area



# Measurement circuits

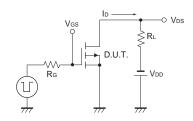


Fig.1-1 Switching Time Measurement Circuit

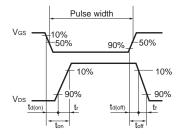


Fig.1-2 Switching Waveforms

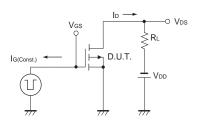


Fig.2-1 Gate Charge Measurement Circuit

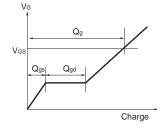


Fig.2-2 Gate Charge Waveform

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Ì	JÁPAN	USA	EU	CHINA	
Γ	CLASSⅢ	CL ACCIII	CLASS II b	CL A C C TT	
Γ	CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ	

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  - [f] Sealing or coating our Products with resin or other coating materials
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  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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